

AN 1986-255498 [39] WPIDS

DNC C1986-110275 [21]

DNN N1986-191044 [21]

TI High strength, electroconductive, heat resistant copper, alloy - containing titanium, and 1 or more of antimony, silver, tellurium, silicon, chromium, cobalt etc.

DC L02; M26; U11; X12

IN AKASAKA K; ASAI M; IWAI H; SHINOZAKI S

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CYC 1

PIA JP 61183426 A 19860816 (198639)* JA 4[0]

ADT JP 61183426 A JP 1985-21471 19850206

PRAI JP 1985-21471 19850206

AB JP 61183426 A UPAB: 20050425

The Cu alloy comprises in weight% 0.05-2.0 Ti, 5.0 or less of one or more of Sb, Ag, Te, Si, Cr, Co, Fe, P, Sn, Mg, Zr, Al, Mn, La, Ce, Y, Be and Ni, and balance Cu and incidental impurities.

USE/ADVANTAGE - The Cu alloy is used for lead frames and connectors especially of semiconductor IC's, and has excellent electrical conductivity, heat resistance, good formability, and platability (solderability), allows thinness and minuatursing, and increased integrity of lead frames. - In an example, Cu alloy comprising (in weight%) 0.1 Ti, 0.2 Sb, and balance Cu, made by melting Cu in graphite crucible under charcoal powder, to which Ti was added, was cast into ingot, the surfaces ground, hot rolled repeatedly cold rolled, process annealed (600 deg.C for 1 hr.) and cold rolled with 40% reduction to 0.25 mm thickness sheet. The Cu alloy sheet obtd. had an electrical conductivity of 76% IACS, tensile strength of 51 kg/mm2, and good adherence to Ag plating.